

Integrated Silicon Pressure Sensor On-Chip Signal Conditioned, Temperature Compensated and Calibrated

The MPVZ5050G series piezoresistive transducer is a state-of-the-art monolithic silicon pressure sensor designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This patented, single element transducer combines advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure.

Features

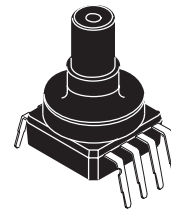
- 2.5% Maximum Error over 0° to 85°C
- Ideally suited for Microprocessor or Microcontroller-Based Systems
- Temperature Compensated Over -40° to +125°C
- Patented Silicon Shear Stress Strain Gauge

ORDERING INFORMATION					
Device Type	Options	Case No.	MPX Series Order No.	Packing Options	Device Marking
SMALL OUTLINE PACKAGE (MPVZ5050G SERIES)					
Ported Elements	Axial Port	1560	MPVZ5050GW7U	Rails	MZ5050GW

MPVZ5050G SERIES

**INTEGRATED
 PRESSURE SENSOR**
 0 to 50 kPa (0 to 7.25 psi)
 0.2 to 4.7 V Output

SMALL OUTLINE PACKAGE



**MPVZ5050GW7U
 CASE 1560-02**

SMALL OUTLINE PACKAGE PIN NUMBERS⁽¹⁾

1	N/C	5	N/C
2	V _S	6	N/C
3	Gnd	7	N/C
4	V _{out}	8	N/C

1. Pins 1, 5, 6, 7, and 8 are internal device connections. Do not connect to external circuitry or ground. Pin 1 is noted by the notch in the lead.

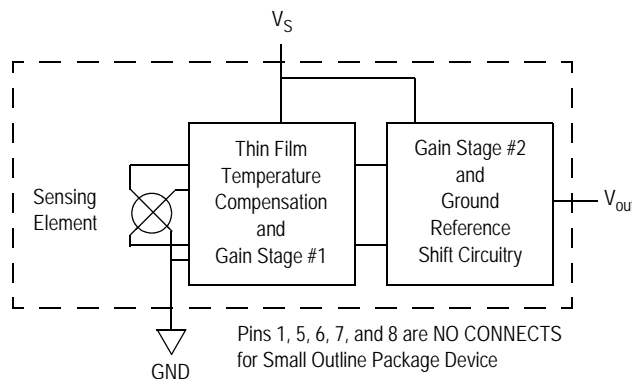


Figure 1. Fully Integrated Pressure Sensor Schematic

Table 1. Maximum Ratings⁽¹⁾

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P _{max}	200	kPa
Storage Temperature	T _{stg}	-40° to +125°	°C
Operating Temperature	T _A	-40° to +125°	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Table 2. . Operating Characteristics (V_S = 5.0 Vdc, T_A = 25°C unless otherwise noted, P1 > P2. Decoupling circuit shown in Figure 4 required to meet electrical specifications.)

Characteristic	Symbol	Min	Typ	Max	Unit
Pressure Range ⁽¹⁾	P _{OP}	0	—	50	kPa
Supply Voltage ⁽²⁾	V _S	4.75	5.0	5.25	Vdc
Supply Current	I _o	—	7.0	10	mAdc
Minimum Pressure Offset ⁽³⁾ @ V _S = 5.0 Volts	V _{off}	0.088	0.2	0.313	Vdc
Full Scale Output ⁽⁴⁾ @ V _S = 5.0 Volts	V _{FSO}	4.587	4.7	4.813	Vdc
Full Scale Span ⁽⁵⁾ @ V _S = 5.0 Volts	V _{FSS}	—	4.5	—	Vdc
Accuracy ⁽⁶⁾	—	—	—	±2.5	%V _{FSS}
Sensitivity	V/P	—	90	—	mV/kPa
Response Time ⁽⁷⁾	t _R	—	1.0	—	ms
Output Source Current at Full Scale Output	I _{o+}	—	0.1	—	mAdc
Warm-Up Time ⁽⁸⁾	—	—	20	—	ms
Offset Stability ⁽⁹⁾	—	—	±0.5	—	%V _{FSS}

- 1.0 kPa (kiloPascal) equals 0.145 psi.
- Device is ratiometric within this specified excitation range.
- Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
- Full Scale Output (V_{FSO}) is defined as the output voltage at the maximum or full rated pressure.
- Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
- Accuracy (error budget) consists of the following:
 - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
 - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
 - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure at 25°C.
 - TcSpan: Output deviation over the temperature range of 0° to 85°C, relative to 25°C.
 - TcOffset: Output deviation with minimum pressure applied, over the temperature range of 0° to 85°C, relative to 25°C.
 - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of V_{FSS} at 25°C.
- Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
- Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
- Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

Figure 3 illustrates the Differential/Gauge Sensing Chip in the basic chip carrier (Case 482A). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm.

The MPVZ5050G series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 2 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 4. The output will saturate outside of the specified pressure range.

Figure 4 shows the recommended decoupling circuit for interfacing the output of the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

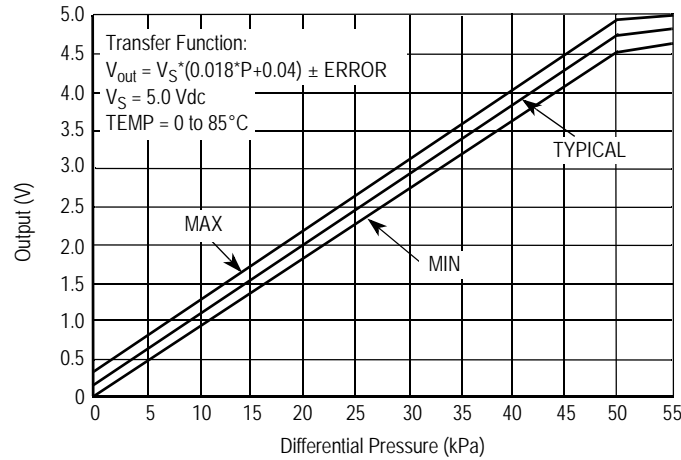


Figure 2. Output versus Pressure Differential

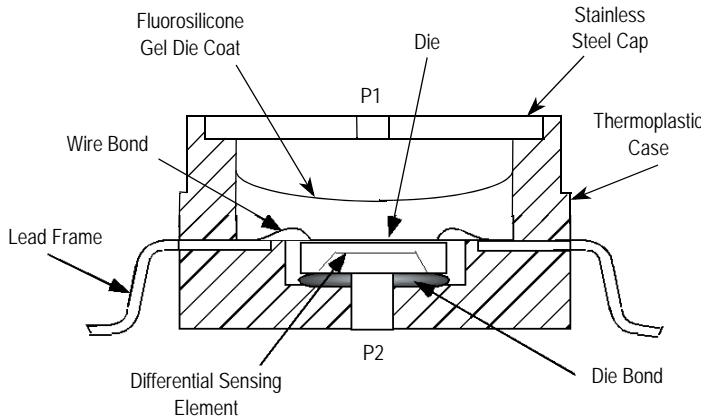


Figure 3. Cross-Sectional Diagram (not to scale)

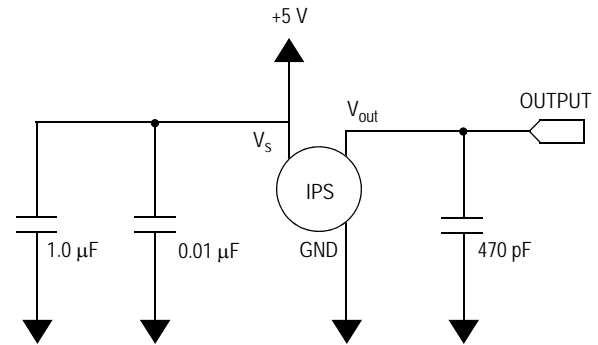


Figure 4. Recommended Power Supply Decoupling and Output Filtering

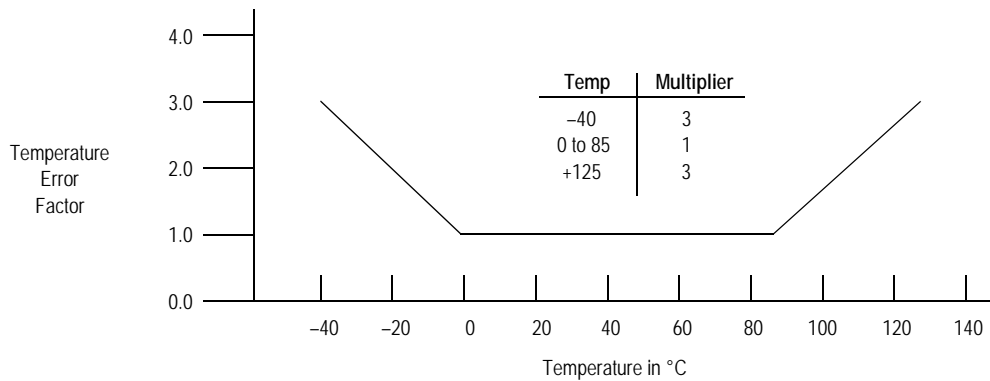
(For additional output filtering, please refer to Application Note AN1646.)

Transfer Function

Nominal Transfer Value: $V_{out} = V_S (P \times 0.018 + 0.04)$
 $\pm (\text{Pressure Error} \times \text{Temp. Factor} \times 0.018 \times V_S)$
 $V_S = 5.0 \text{ V} \pm 0.25 \text{ Vdc}$

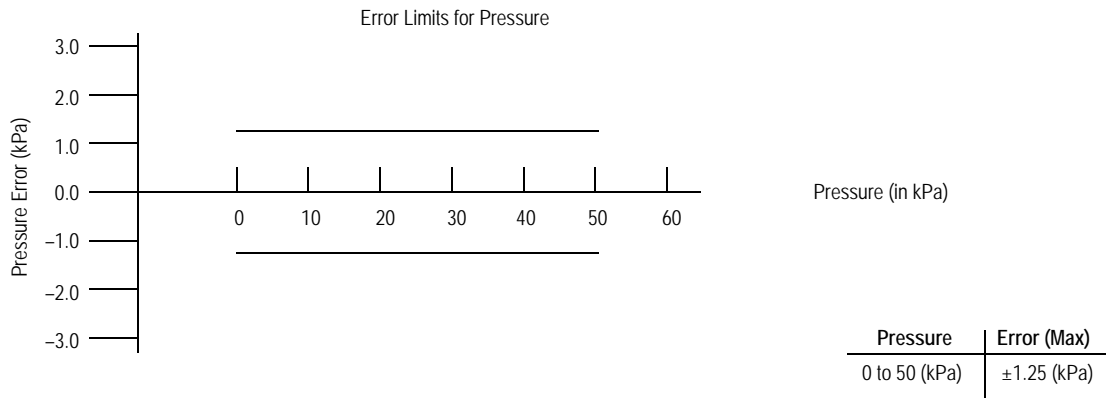
Temperature Error Band

MPVZ5050G SERIES



NOTE: The Temperature Multiplier is a linear response from 0° to -40°C and from 85° to 125°C.

Pressure Error Band



PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

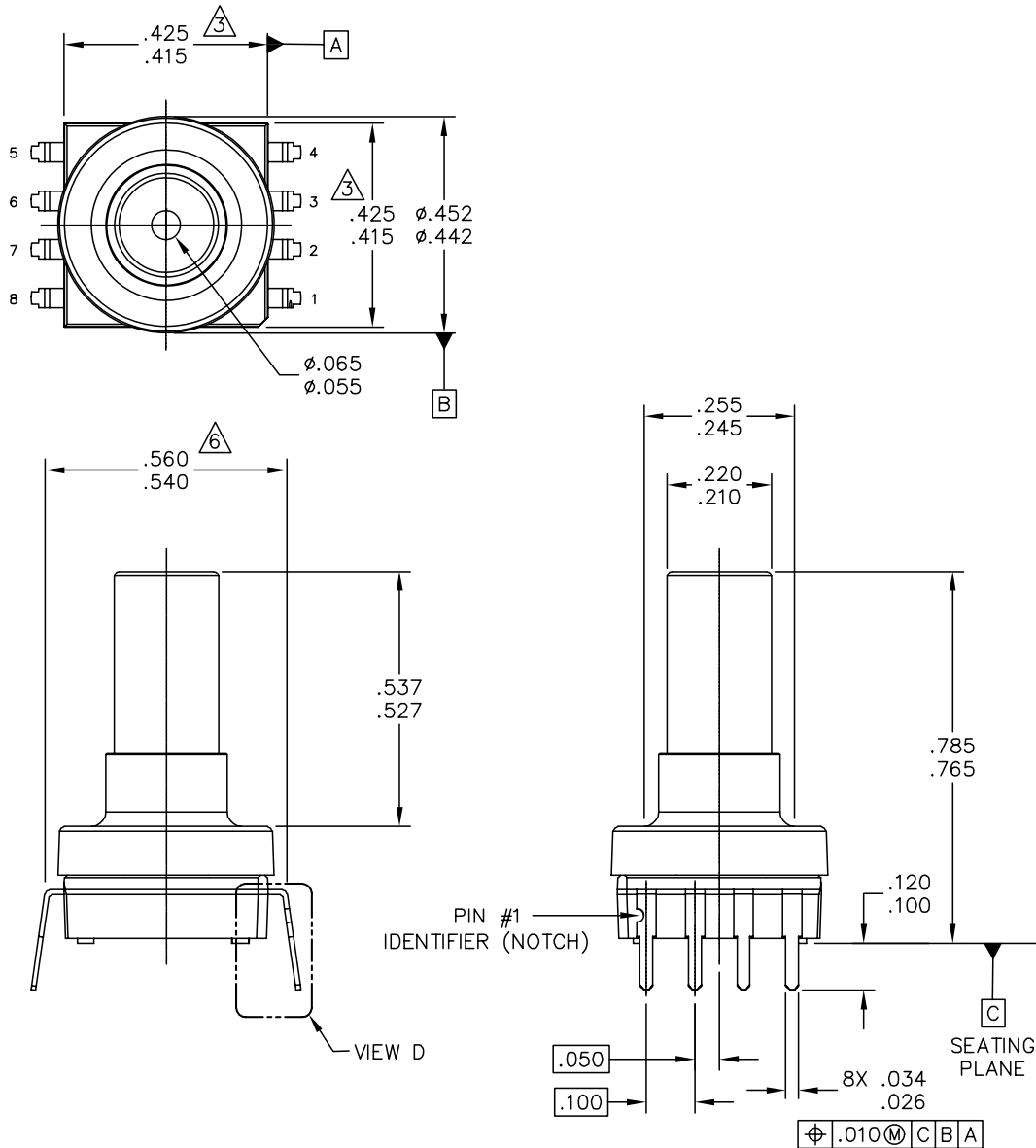
Freescle designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing fluorosilicone gel which protects the die from harsh media. The MPX pressure

sensor is designed to operate with positive differential pressure applied, $P1 > P2$.

The Pressure (P1) side may be identified by using the table below:

Part Number	Case Type	Pressure (P1) Side Identifier
MPVZ5050GW7U	1560-02	Vertical Port Attached

PACKAGE DIMENSIONS



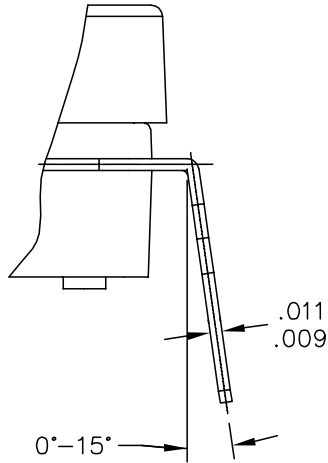
© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH	DOCUMENT NO: 98ASA10611D	REV: C
	CASE NUMBER: 1560-02	26 MAY 2005
	STANDARD: NON-JEDEC	

PAGE 1 OF 3

CASE 1560-02 ISSUE C SMALL OUTLINE PACKAGE

MPVZ5050

PACKAGE DIMENSIONS



VIEW D

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH	DOCUMENT NO: 98ASA10611D	REV: C	
	CASE NUMBER: 1560-02	26 MAY 2005	
	STANDARD: NON-JEDEC		

PAGE 2 OF 3

**CASE 1560-02
ISSUE C
SMALL OUTLINE PACKAGE**

PACKAGE DIMENSIONS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M – 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION IS .006.
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.
6. DIMENSION TO CENTER OF LEAD WHEN FORMED PARALLEL.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH	DOCUMENT NO: 98ASA10611D	REV: C	
	CASE NUMBER: 1560-02	26 MAY 2005	
	STANDARD: NON-JEDEC		

PAGE 3 OF 3

**CASE 1560-02
ISSUE C
SMALL OUTLINE PACKAGE**

MPVZ5050

How to Reach Us:

Home Page:

www.freescale.com

Web Support:

<http://www.freescale.com/support>

USA/Europe or Locations Not Listed:

Freescale Semiconductor, Inc.
Technical Information Center, EL516
2100 East Elliot Road
Tempe, Arizona 85284
+1-800-521-6274 or +1-480-768-2130
www.freescale.com/support

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
www.freescale.com/support

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
1-800-441-2447 or 303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© Freescale Semiconductor, Inc. 2007. All rights reserved.

